



Material Content Data Sheet



Sales Product Name				IKFW50N60DH3		Issued		2. August 2018	
MA#				MA001674414					
Package				PG-HSIP247-3-1		Weight*		5792.58 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	0.970	0.02	0.02	167	167	
chip_2	inorganic material	silicon	7440-21-3	3.815	0.07	0.07	659	659	
leadframe	inorganic material	phosphorus	7723-14-0	0.164	0.00		28		
	non noble metal	iron	7439-89-6	0.545	0.01		94		
	non noble metal	copper	7440-50-8	544.561	9.40	9.41	94010	94132	
	non noble metal	aluminium	7429-90-5	12.254	0.21	0.21	2115	2115	
wire	inorganic material	zinc oxide	1314-13-2	0.576	0.01		99		
encapsulation	plastics	silicone resin	-	1.296	0.02		224		
	inorganic material	alumina	1344-28-1	12.526	0.22		2162		
	organic material	carbon black	1333-86-4	21.855	0.38		3773		
	plastics	epoxy resin	-	415.245	7.17		71686		
	inorganic material	silicon dioxide	60676-86-0	1748.401	30.18	37.98	301835	379779	
leadfinish	non noble metal	tin	7440-31-5	16.291	0.28	0.28	2812	2812	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.456	0.01	0.01	79	80	
solder	non noble metal	antimony	7440-36-0	0.354	0.01		61		
	noble metal	silver	7440-22-4	0.885	0.02		153		
	non noble metal	tin	7440-31-5	2.301	0.04	0.07	397	611	
heatspreader	inorganic material	phosphorus	7723-14-0	0.903	0.02		156		
	non noble metal	iron	7439-89-6	3.010	0.05		520		
	non noble metal	copper	7440-50-8	3006.169	51.88	51.95	518969	519645	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com